

C1, mod acids, thiosalicylic acids, and mixtures thereof, (iv) at least one passivation film-forming agent, and (v) a polishing pad and/or an abrasive.

8. (Amended) The system of claim 3, wherein at least one oxidizing agent is a peroxide, and at least one passivation film forming agent comprises one or more 5-6 member heterocyclic nitrogen-containing rings.

C2 9. (Amended) The system of claim 3, wherein at least one polishing additive is selected from the group consisting of ethylene di-phosphonic acid, 1-hydroxyethylidene-1,1-di-phosphonic acid, and a mixture thereof.

C3 16. (Amended) The system of claim 9, wherein at least one oxidizing agent is a peroxide, and at least one passivation film forming agent comprises one or more 5-6 member heterocyclic nitrogen-containing rings.

C4 24. (Amended) The system of claim 3, wherein at least one passivation film-forming agent is selected from the group consisting of 1,2,3-triazole, 1,2,4-triazole, benzotriazole, benzimidazole, benzothiazole, and hydroxy-, amino-, imino-, carboxy-, mercapto-, nitro-, urea-, thiourea-, or alkyl-substituted derivatives thereof.

REMARKS

Information Disclosure Statement

Applicants have received a copy of the Examiner-initialed Form PTO-1449 identifying references AQ-AV, but noted that reference AS has not been initialed. Applicants respectfully request confirmation of the consideration of reference AS by return copy of the Examiner-initialed Form PTO-1449 showing the Examiner's initials next to the identification of reference AS.

The Pending Claims

Claims 1-6, 8, 9, 16-27, and 32-35 are currently pending. Claims 1-6, 8, 9, 16-27, and 32-35 are directed to a system for polishing one or more layers of a multi-layer substrate comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, (iv) at least one passivation film-forming agent, and (v) a polishing pad and/or an abrasive.